



## Material Content Data Sheet



<b>Sales Product Name</b>		IPG20N10S4L-22		<b>Issued</b>		31. July 2018		
<b>MA#</b>		MA000940698						
<b>Package</b>		PG-TDSON-8-4		<b>Weight*</b>		97.52 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.592	1.63	1.63	16323	16323
chip_2	inorganic material	silicon	7440-21-3	1.592	1.63	1.63	16323	16323
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		138	
	non noble metal	iron	7439-89-6	0.045	0.05		458	
	non noble metal	copper	7440-50-8	44.654	45.80	45.86	457891	458487
	non noble metal	aluminium	7429-90-5	0.696	0.71	0.71	7136	7136
wire	non noble metal	aluminium	7429-90-5	0.696	0.71	0.71	7136	7136
	organic material	carbon black	1333-86-4	0.088	0.09		904	
encapsulation	plastics	epoxy resin	-	6.260	6.42		64194	
	inorganic material	silicondioxide	60676-86-0	37.738	38.70	45.21	386973	452071
leadfinish	non noble metal	tin	7440-31-5	1.308	1.34	1.34	13409	13409
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.048	0.05	0.05	492	493
solder	non noble metal	tin	7440-31-5	0.070	0.07		715	
	noble metal	silver	7440-22-4	0.087	0.09		894	
	non noble metal	lead	7439-92-1	3.330	3.41	3.57	34149	35758
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com